TPS3711 36V 電圧検出器

1 特長

- 広い電源電圧範囲:1.8 V～36 V
- スレッショルドを変更可能:最小 400mV
- 低電圧検出用のオープン ドレイン出力
- 低い静止電流:7µA (標準値)
- 高いスレッショルド精度:
  - 0.75% 過熱
  - 0.25% (標準値)
- 内部ヒステリシス:5.5 mV (標準値)
- 温度範囲:-40℃～+125℃
- パッケージ:SOT-6

2 アプリケーション

- 産業用制御システム
- 組み込みコンピューティング・モジュール
- DSP、マイクロコントローラ、マイクロプロセッサ
- ノート PC およびデスクトップ PC
- 携帯用およびバッテリ駆動製品
- FPGA および ASIC システム

3 概要

TPS3711 は電源電圧範囲の広いコンパレータで、1.8V ～36V の範囲で動作します。高精度コンパレータと 400mV の基準電圧に加え、低電圧検出用に定格 25V のオープン ドレイン出力を内蔵しています。監視対象の電圧は外付け抵抗により設定できます。

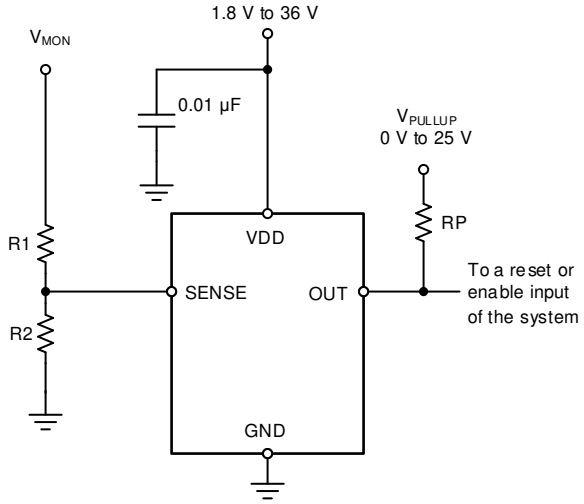
SENSE ピンの電圧が負のスレッショルドを下回ると OUT が LOW になり、正のスレッショルドを上回ると HIGH になります。TLV3711 のコンパレータにはノイズ除去のヒステリシスが組み込まれているため、誤ったトリガが発生せず、安定した出力動作が確保されます。

TPS3711 は SOT-6 パッケージで供給され、-40°C ～+125°C の接合部温度範囲で動作が規定されています。

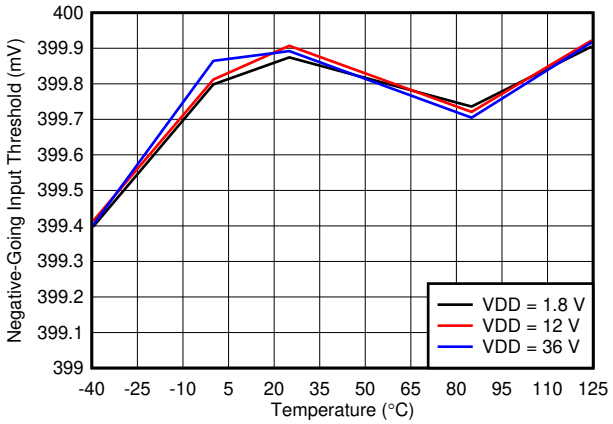
製品情報

部品番号	パッケージ (1)	本体サイズ (公称)
TPS3711	SOT (6)	2.90mm×1.60mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にあるパッケージ・オプションについての付録を参照してください。



代表的なアプリケーション



標準的な誤差と接合部温度との関係

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4 Pin Configuration and Functions

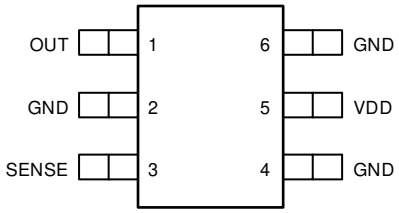


図 4-1. DDC Package
6-Pin SOT
Top View

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
GND	2, 4, 6	—	Ground. Connect all three pins to ground.
OUT	1	O	Comparator open-drain output. This pin is driven low when the voltage at this comparator is less than V_{IT-}. The output goes high when the sense voltage rises above V_{IT+}.
SENSE	3	I	Comparator input. This pin is connected to the voltage to be monitored with the use of an external resistor divider. When the voltage at this pin drops below the threshold voltage V_{IT-}, OUT is driven low.
VDD	5	I	Supply-voltage input. Connect a 1.8-V to 36-V supply to VDD to power the device. It is good analog design practice to place a 0.1-µF ceramic capacitor close to this pin.

5 Specifications

5.1 Absolute Maximum Ratings (1)

over operating junction temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Voltage (2)	V_{DD}	–0.3	40	V
	V_{OUT}	–0.3	28	
	V_{SENSE}	–0.3	7	
Current	Output pin current		40	mA
Temperature	Operating junction, T_J	–40	125	°C
	Storage, T_{stg}	–55	125	

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network ground terminal.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating junction temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{DD}	Supply pin voltage	1.8		36	V
V_{SENSE}	Input pin voltage	0		6.5(1)	V
V_{OUT}	Output pin voltage	0		25	V
V_{PULLUP}	Pullup voltage	0		25	V
I_{OUT}	Output pin current	0		10	mA
T_J	Junction temperature	–40	25	125	°C

(1) Operating V_{sense} at 1.7 V or higher and at 125°C continuously for 10 years or more would cause a degradation of accuracy spec to 1.5% maximum.

5.4 Thermal Information

THERMAL METRIC		TPS3711 DDC (SOT) 6 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	201.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	47.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	51.2	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	50.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

5.5 Electrical Characteristics

Over the operating temperature range of T_J = –40°C to +125°C, 1.8 V ≤ V_{DD} < 36 V, and pullup resistor RP = 100 kΩ (unless otherwise noted). Typical values are at T_J = 25°C and V_{DD} = 12 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(POR)}$	Power-on reset voltage(1)	V_{OL} ≤ 0.2 V			0.8	V
$V_{IT–}$	SENSE pin negative input threshold voltage	V_{DD} = 1.8 V to 36 V	397	400	403	mV
V_{IT+}	SENSE pin positive input threshold voltage	V_{DD} = 1.8 V to 36 V	400	405.5	413	mV
V_{HYS}	SENSE pin hysteresis voltage ($HYS = V_{IT+} – V_{IT–}$)		2	5.5	12	mV
V_{OL}	Low-level output voltage	V_{DD} = 1.8 V, I_{OUT} = 3 mA		130	250	mV
		V_{DD} = 5 V, I_{OUT} = 5 mA		150	250	
I_{IN}	Input current (at SENSE pin)	V_{DD} = 1.8 V and 36 V, V_{SENSE} = 6.5 V	–25	+1	+25	nA
		V_{DD} = 1.8 V and 36 V, V_{SENSE} = 0.1 V	–15	+1	+15	
$I_{D(leak)}$	Open-drain leakage current	V_{DD} = 1.8 V and 36 V, V_{OUT} = 25 V		10	300	nA
I_{DD}	Supply current	V_{DD} = 1.8 V – 36 V		8	11	µA
UVLO	Undervoltage lockout(2)	V_{DD} falling	1.3	1.5	1.7	V

(1) The lowest supply voltage (V_{DD}) at which output is active; $t_{r(VDD)}$ > 15 µs/V. If less than $V_{(POR)}$, the output is undetermined.
(2) When V_{DD} falls below UVLO, OUT is driven low. The output cannot be determined if less than $V_{(POR)}$.

5.6 Timing Requirements

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
$t_{pd(HL)}$	High-to-low propagation delay(1)	V_{DD} = 24 V, ±10-mV input overdrive, R_L = 100 kΩ, V_{OH} = 0.9 × V_{DD}, V_{OL} = 250 mV		9.9		µs
$t_{pd(LH)}$	Low-to-high propagation delay(1)	V_{DD} = 24 V, ±10-mV input overdrive, R_L = 100 kΩ, V_{OH} = 0.9 × V_{DD}, V_{OL} = 250 mV		28.1		µs
$t_{d(start)}$ (2)	Startup delay	V_{DD} = 5 V		155		µs
t_r	Output rise time	V_{DD} = 12 V, 10-mV input overdrive, R_L = 100 kΩ, C_L = 10 pF, V_O = (0.1 to 0.9) × V_{DD}		2.7		µs
t_f	Output fall time	V_{DD} = 12 V, 10-mV input overdrive, R_L = 100 kΩ, C_L = 10 pF, V_O = (0.9 to 0.1) × V_{DD}		0.12		µs

(1) High-to-low and low-to-high refers to the transition at the input pin (SENSE).
(2) During power on, V_{DD} must exceed 1.8 V for at least 150 µs (typ) before the output state reflects the input condition.

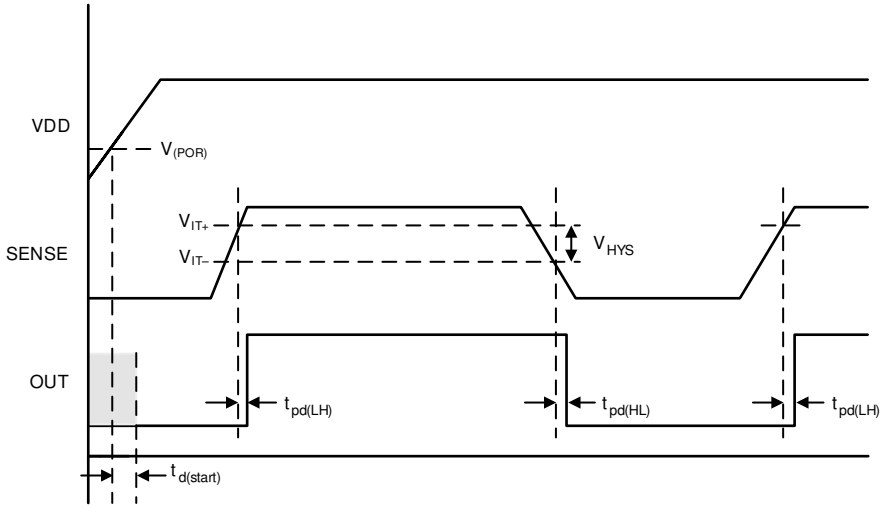


図 5-1. Timing Diagram

5.7 Typical Characteristics

at T_J = 25°C and V_{DD} = 12 V (unless otherwise noted)

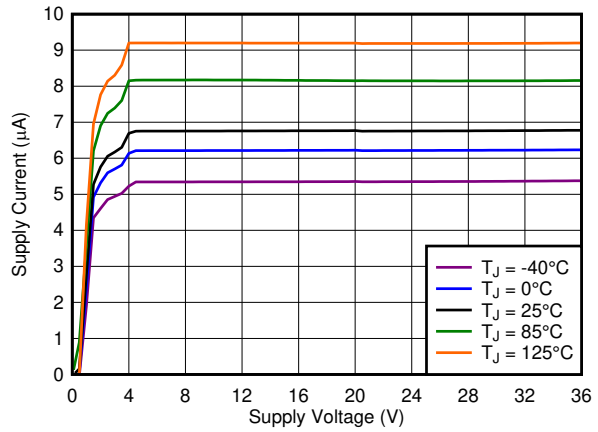
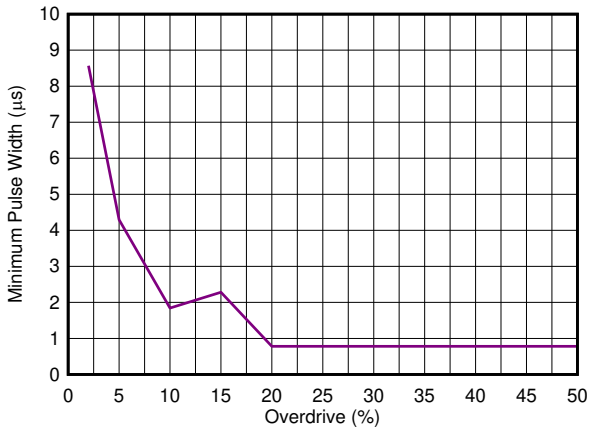


図 5-2. Supply Current vs Supply Voltage



V_{DD} = 24 V, minimum pulse duration required to trigger output high-to-low transition, SENSE = negative spike below V_{IT-}

図 5-3. Minimum Pulse Duration vs Threshold Overdrive Voltage

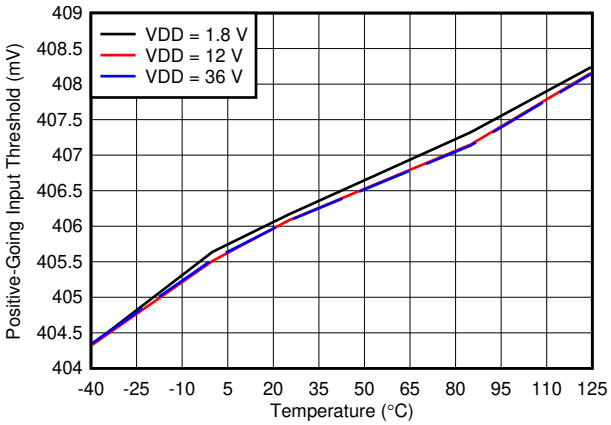


図 5-4. SENSE Positive Input Threshold Voltage (V_{IT+}) vs Temperature

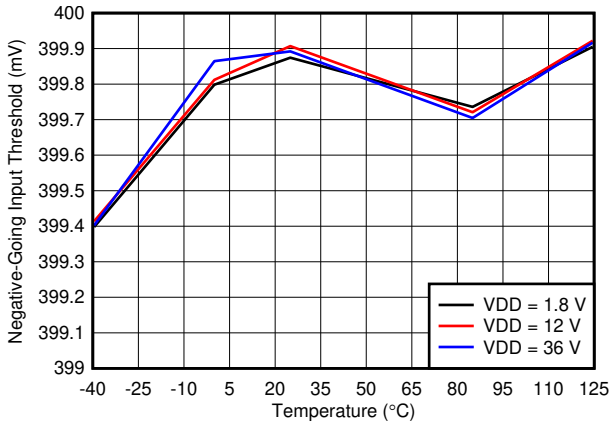


図 5-5. SENSE Negative Input Threshold Voltage (V_{IT-}) vs Temperature

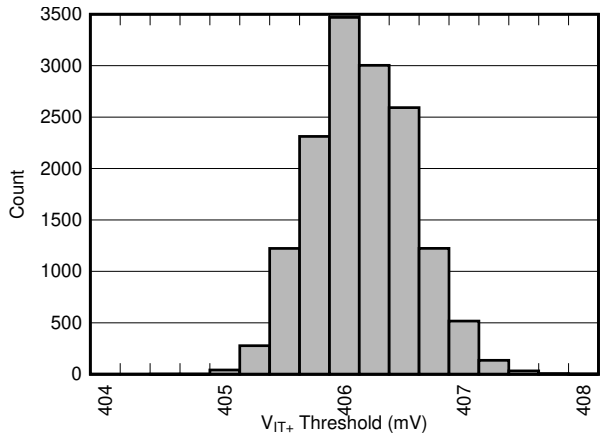


図 5-6. SENSE Positive Input Threshold Voltage (V_{IT+}) Distribution

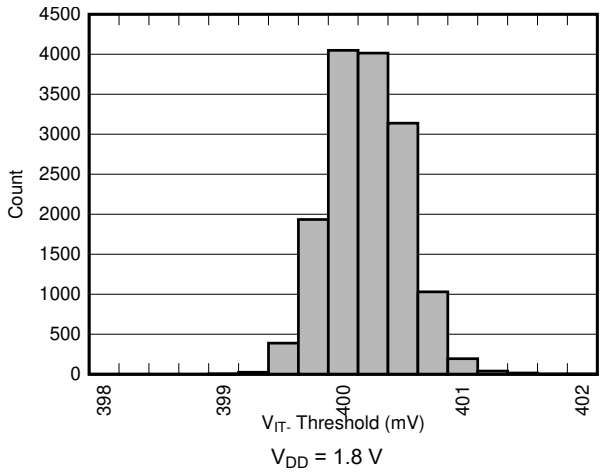


図 5-7. SENSE Negative Input Threshold Voltage (V_{IT-}) Distribution

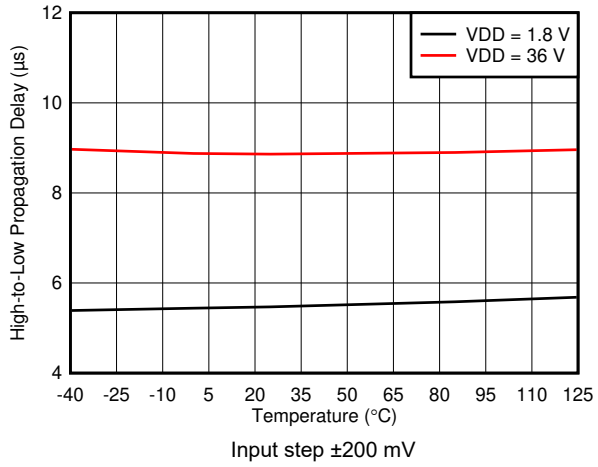


図 5-8. Propagation Delay vs Temperature (High-to-Low Transition at SENSE)

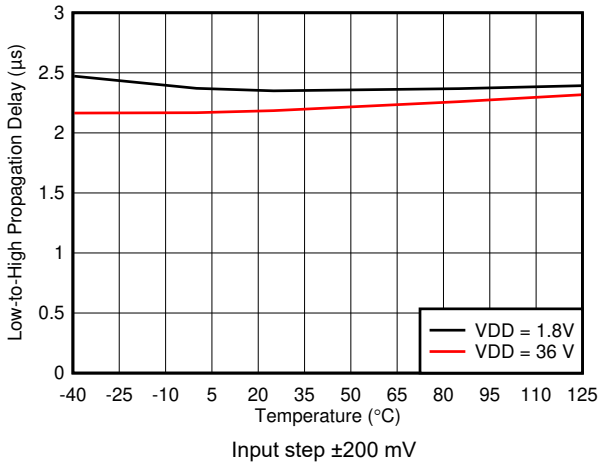


図 5-9. Propagation Delay vs Temperature (Low-to-High Transition at SENSE)

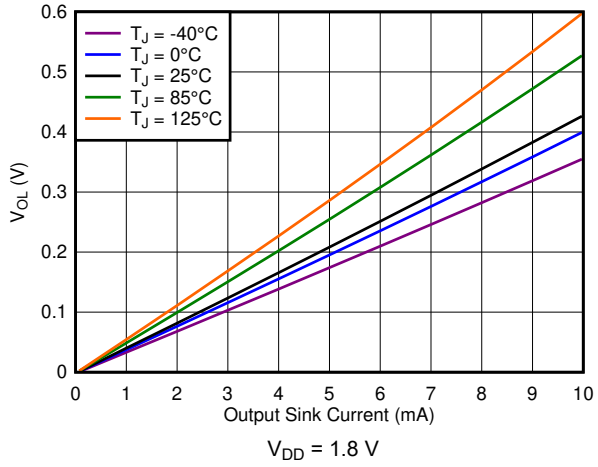


図 5-10. Output Voltage Low vs Output Sink Current

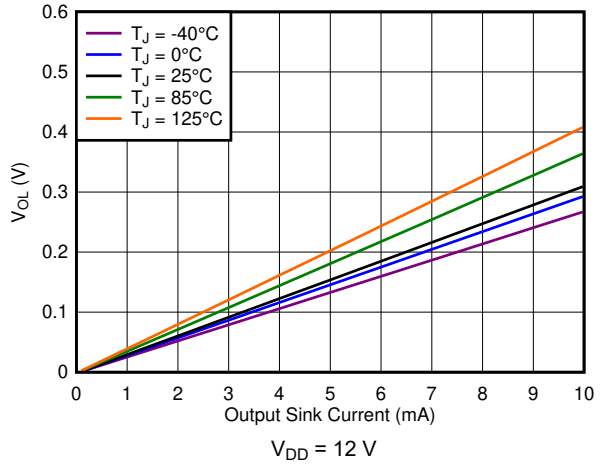


図 5-11. Output Voltage Low vs Output Sink Current

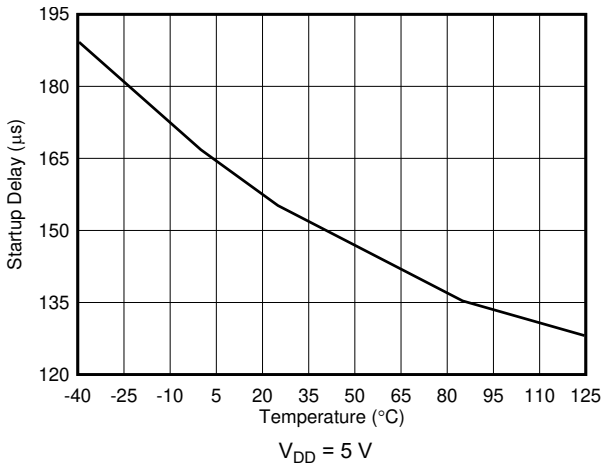


図 5-12. Startup Delay vs Temperature

6 Detailed Description

6.1 Overview

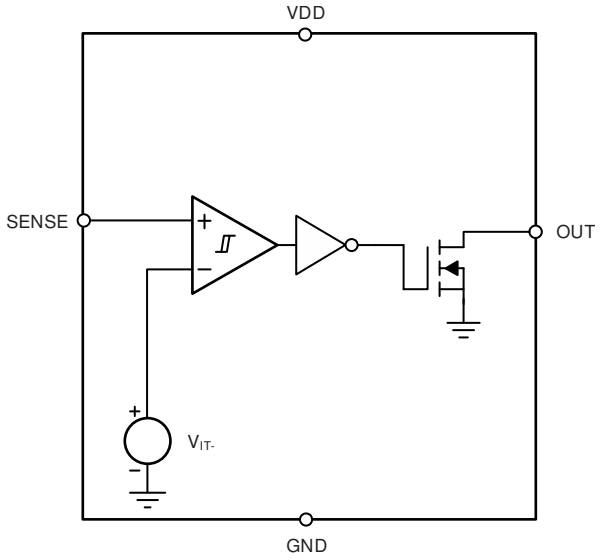
The TPS3711 combines a comparator and a precision reference for undervoltage detection. The TPS3711 features a wide supply voltage range (1.8 V to 36 V) and a high-accuracy threshold voltage of 400 mV (0.75% overtemperature) with built-in hysteresis. The output is rated to 25 V and can sink up to 10 mA.

Set the input pin (SENSE) to monitor any voltage above 0.4 V by using an external resistor divider network. SENSE has very low input leakage current, allowing the use of a large resistor divider without sacrificing system accuracy. The relationship between the input and the output is shown in 表 6-1. Broad voltage thresholds are supported that enable the device to be used in a wide array of applications.

表 6-1. Truth Table

CONDITION	OUTPUT	STATUS
SENSE > V_{IT+}	OUT high	Output high impedance
SENSE < V_{IT-}	OUT low	Output asserted

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Input Pin (SENSE)

The TPS3711 combines a comparator with a precision reference voltage. The comparator has one external input and one internal input connected to the internal reference. The falling threshold on SENSE is designed and trimmed to be equal to the reference voltage (400 mV). This configuration optimizes the device accuracy. The comparator also has built-in hysteresis that proves immunity to noise and ensures stable operation.

The comparator input swings from ground to 6.5 V (7.0 V absolute maximum), regardless of the device supply voltage used. Although not required in most cases, it is good analog design practice to place a 1-nF to 10-nF bypass capacitor at the comparator input for noisy applications in order to reduce sensitivity to transient voltage changes on the monitored signal.

For the comparator, the output (OUT) is driven to logic low when the input SENSE voltage drops below V_{IT-}. When the voltage exceeds V_{IT+}, OUT goes to a high-impedance state; see 図 5-1.

6.3.2 Output Pin (OUT)

In a typical TPS3711 application, the output is connected to a reset or enable input of the processor [such as a digital signal processor (DSP), application-specific integrated circuit (ASIC), or other processor type] or the output is connected to the enable input of a voltage regulator [such as a dc-dc converter or low-dropout regulator (LDO)].

The TPS3711 provides an open-drain output (OUT); use a pullup resistor to hold the line high when the output goes to a high-impedance state. Connect this pullup resistor to a voltage rail that meets the logic requirements of the downstream device. The TPS3711 output can be pulled up to 25 V, independent of the device supply voltage. To make sure the proper voltage level, give some consideration when choosing the pullup resistor value. The pullup resistor value is determined by V_{OL}, output capacitive loading, and the open-drain leakage current ($I_{D(leak)}$). These values are specified in the *セクション 5.5* table.

表 6-1 and the *セクション 6.3.1* section describe how the output is asserted or high impedance. See 図 5-1 for a timing diagram that describes the relationship between threshold voltage and the respective output.

6.4 Device Functional Modes

6.4.1 Normal Operation (V_{DD} > UVLO)

When the voltage on VDD is greater than 1.8 V for at least 155 µs, the OUT signal corresponds to the voltage on SENSE, as listed in 表 6-1.

6.4.2 Undervoltage Lockout ($V_{(POR)} < V_{DD} <$ UVLO)

When the voltage on VDD is less than the device UVLO voltage, and greater than the power-on reset voltage, $V_{(POR)}$, the OUT signal is asserted regardless of the voltage on SENSE.

6.4.3 Power On Reset ($V_{DD} < V_{(POR)}$)

When the voltage on VDD is lower than the required voltage to internally pull the asserted output to GND ($V_{(POR)}$), OUT is in a high-impedance state.

7 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

7.1 Application Information

The TPS3711 is used as a precision voltage supervisor in several different configurations. The monitored voltage (V_{MON}), VDD voltage, and output pullup voltage can be independent voltages or connected in any configuration. The following sections show the connection configurations and the voltage limitations for each configuration.

7.1.1 Input and Output Configurations

図 7-1 to 図 7-2 show examples of the various input and output configurations.

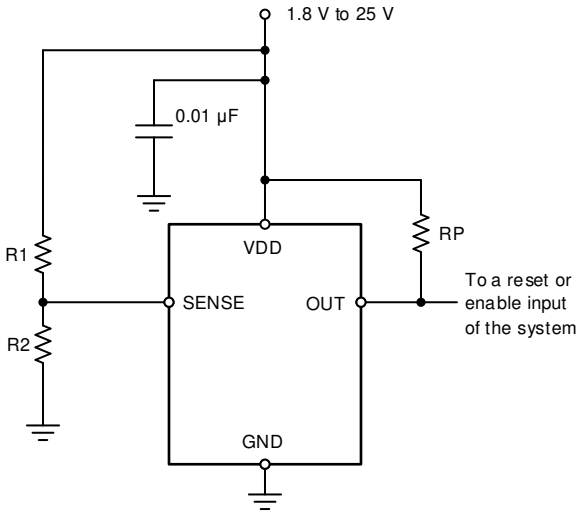
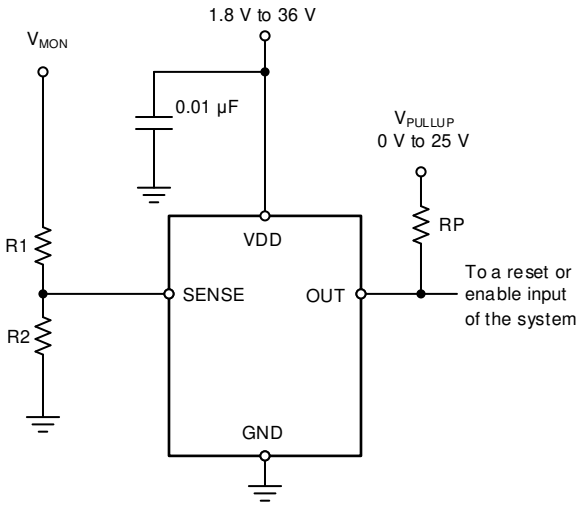


図 7-1. Monitoring the Same Voltage as V_{DD}



NOTE: The input can monitor a voltage higher than V_{DD} (max) with the use of an external resistor divider network.

図 7-2. Monitoring a Voltage Other than V_{DD}

7.1.2 Immunity to Input Pin Voltage Transients

The TPS3711 is immune to short voltage transient spikes on the input pin. Sensitivity to transients depends on both transient duration and amplitude; see 図 5-3, *Minimum Pulse Duration vs Threshold Overdrive Voltage*.

7.2 Typical Application

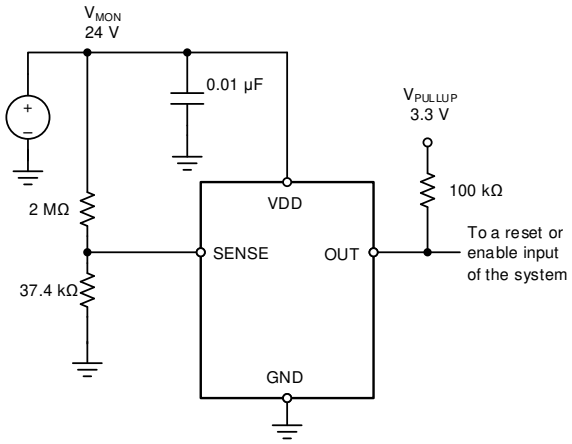


図 7-3. 24-V, 10% Comparator

7.2.1 Design Requirements

表 7-1. Design Parameters

PARAMETER	DESIGN REQUIREMENT	DESIGN RESULT
Monitored voltage	24-V nominal, falling ($V_{MON(UV)}$) threshold 10% nominal (21.6 V)	$V_{MON(UV)}$ = 21.8 V ±2.7%
Output logic voltage	3.3-V CMOS	3.3-V CMOS
Maximum current consumption	30 µA	24 µA

7.2.2 Detailed Design Procedure

7.2.2.1 Resistor Divider Selection

The resistor divider values and target threshold voltage can be calculated by using 式 1 to determine $V_{MON(UV)}$.

$$V_{MON(UV)} = \left(1 + \frac{R1}{R2}\right) \times V_{IT-} \quad (1)$$

where

- R1 and R2 are the resistor values for the resistor divider on the SENSE pin
- $V_{MON(UV)}$ is the target voltage at which an undervoltage condition is detected

Choose an R_{TOTAL} (= R1 + R2) so that the current through the divider is approximately 100 times higher than the input current at the SENSE pin. Use resistors with high values to minimize current consumption (as a result of low input bias current) without adding significant error to the resistive divider. For details on sizing input resistors, refer to application report SLVA450, *Optimizing Resistor Dividers at a Comparator Input*, available for download from www.ti.com.

7.2.2.2 Pullup Resistor Selection

To make sure the proper logic-high voltage level (V_{HI}), select a pullup resistor value where the pullup voltage divided by the pullup resistor value does not exceed the sink-current capability of the device. Confirm this voltage level by verifying that the pullup voltage minus the open-drain leakage current ($I_{D(leak)}$) multiplied by the resistor is greater than the desired V_{HI}. These values are specified in the セクション 5.5 .

Use 式 2 to calculate the value of the pullup resistor.

$$\frac{V_{HI} - V_{pullup}}{I_{D(leak)}} \leq RP \leq \frac{V_{pullup}}{I_{OUT}} \quad (2)$$

7.2.2.3 Input Supply Capacitor

Although an input capacitor is not required for stability, for good analog design practice, connect a 0.1-µF low equivalent series resistance (ESR) capacitor across the VDD and GND pins. A higher-value capacitor may be necessary if large, fast rise-time load transients are anticipated, or if the device is not located close to the power source.

7.2.3 Application Curves

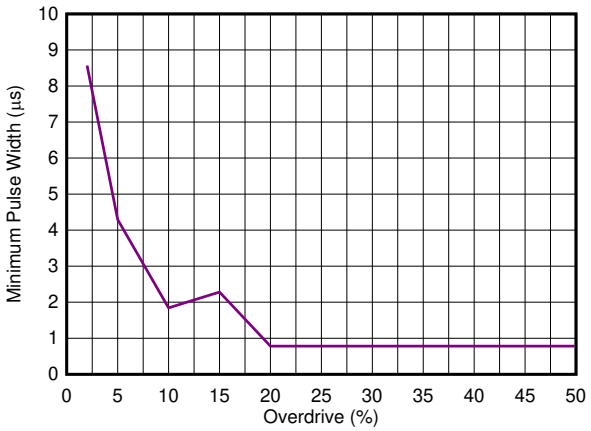


図 7-4. 24-V Window Monitor Output Response

7.3 Power Supply Recommendations

The TPS3711 has a 40-V absolute maximum rating on the VDD pin, with a recommended maximum operating condition of 36 V. If the voltage supply that provides power to VDD is susceptible to any large voltage transient that may exceed 40 V, or if the supply exhibits high voltage slew rates greater than 1 V/µs, then place an RC filter between the supply and VDD to filter any high-frequency transient surges on the VDD pin. In these cases, a 100-Ω resistor and 0.01-µF capacitor are required, as shown in 図 7-5.

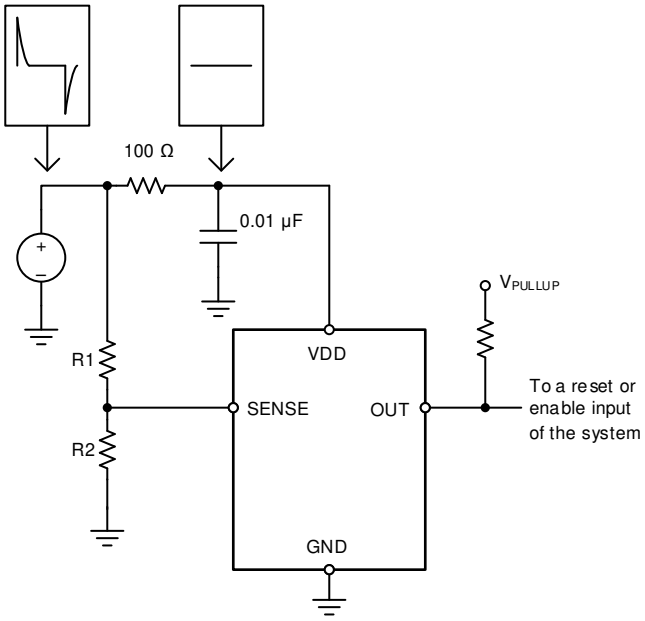


図 7-5. Using an RC Filter to Remove High-Frequency Disturbances on VDD

7.4 Layout

7.4.1 Layout Guidelines

- Place R_1 and R_2 close to the device to minimize noise coupling into the SENSE node.
- Place the VDD decoupling capacitor close to the device.
- Avoid using long traces for the VDD supply node. The VDD capacitor (C_{VDD}), along with parasitic inductance from the supply to the capacitor, might form an LC tank and create ringing with peak voltages above the maximum VDD voltage. If long traces are unavoidable, see 図 7-5 for an example of filtering VDD.

7.4.2 Layout Example

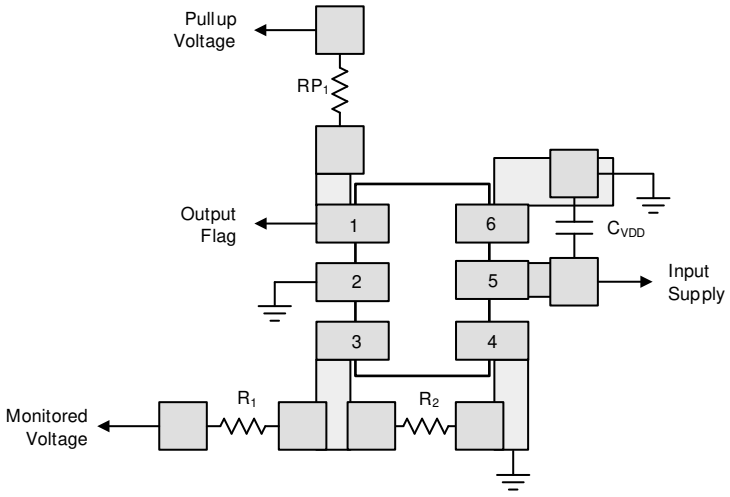


図 7-6. Recommended Layout

8 Device and Documentation Support

8.1 Documentation Support

8.1.1 Related Documentation

For related documentation, see the following application report, available through the TI website at www.ti.com:

- *Optimizing Resistor Dividers at a Comparator Input*, SLVA450

8.2 サポート・リソース

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8.3 Trademarks

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すべての商標は、それぞれの所有者に帰属します。

8.4 静電気放電に関する注意事項

この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

8.5 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

9 Revision History

Changes from Revision A (November 2015) to Revision B (December 2023)	Page
• ドキュメント全体にわたって表、図、相互参照の採番方法を更新	1
• Updated storage temperature range	4

Changes from Revision * (November 2015) to Revision A ()	Page
• Changed input pin voltage maximum value from 1.7 V to 6.5 V	4
• Added tablenote	4

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3711DDCR	Active	Production	SOT-23-THIN (DDC) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO
TPS3711DDCR.A	Active	Production	SOT-23-THIN (DDC) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO
TPS3711DDCT	Active	Production	SOT-23-THIN (DDC) | 6	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO
TPS3711DDCT.A	Active	Production	SOT-23-THIN (DDC) | 6	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO
TPS3711DDCTG4	Active	Production	SOT-23-THIN (DDC) | 6	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO
TPS3711DDCTG4.A	Active	Production	SOT-23-THIN (DDC) | 6	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	11BO

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

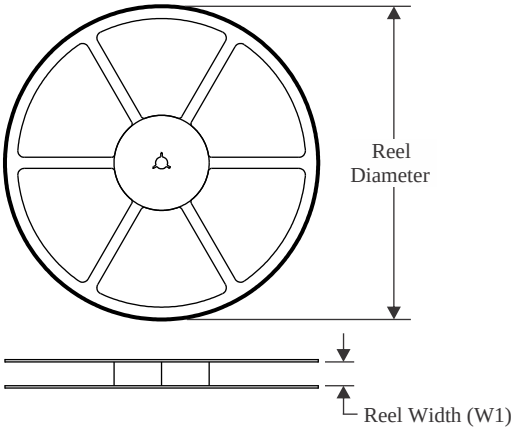
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

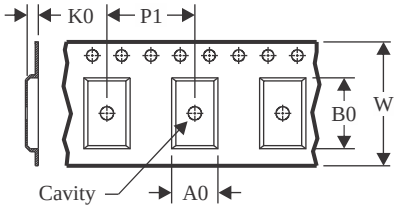
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

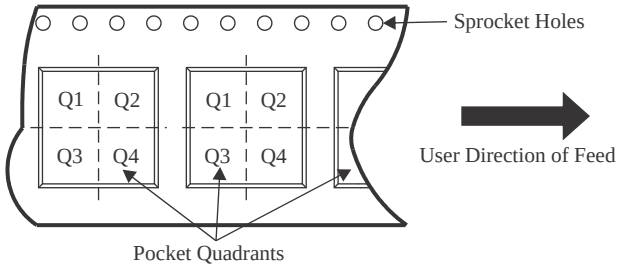


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

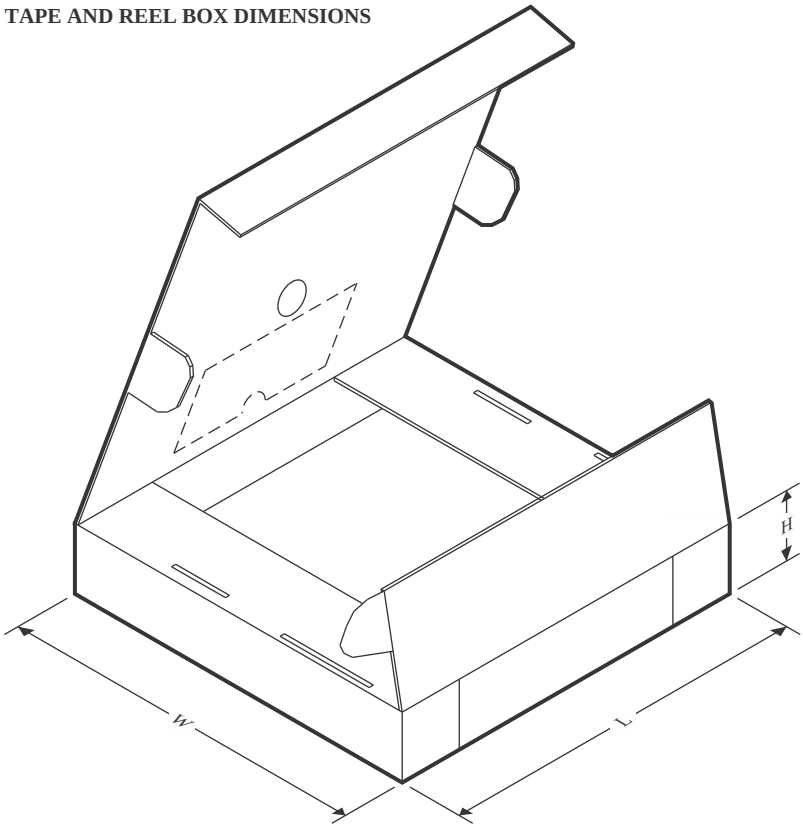
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3711DDCR	SOT-23-THIN	DDC	6	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3711DDCT	SOT-23-THIN	DDC	6	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3711DDCTG4	SOT-23-THIN	DDC	6	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

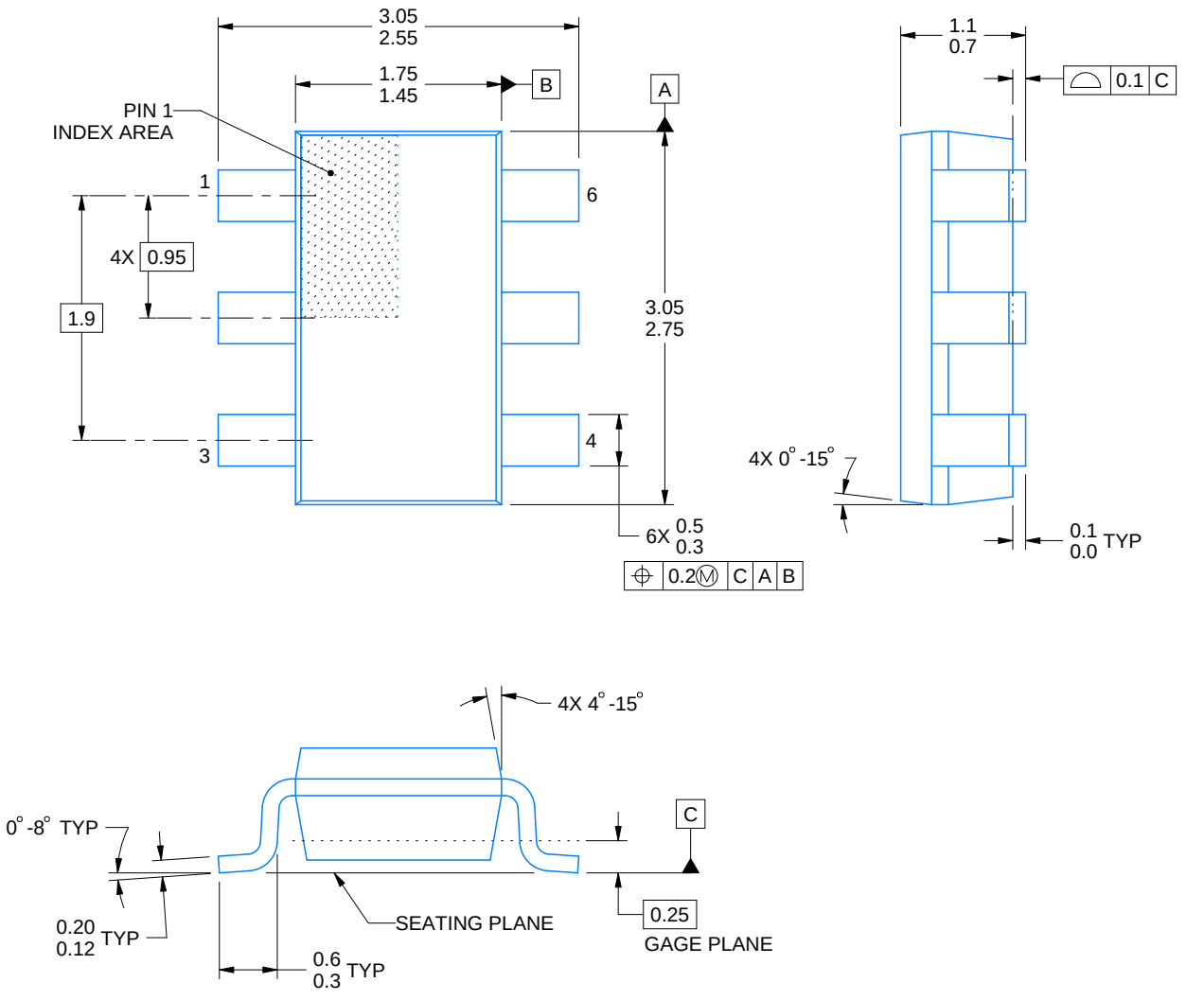
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3711DDCR	SOT-23-THIN	DDC	6	3000	213.0	191.0	35.0
TPS3711DDCT	SOT-23-THIN	DDC	6	250	213.0	191.0	35.0
TPS3711DDCTG4	SOT-23-THIN	DDC	6	250	213.0	191.0	35.0

PACKAGE OUTLINE

DDC0006A

SOT-23 - 1.1 max height

SMALL OUTLINE TRANSISTOR



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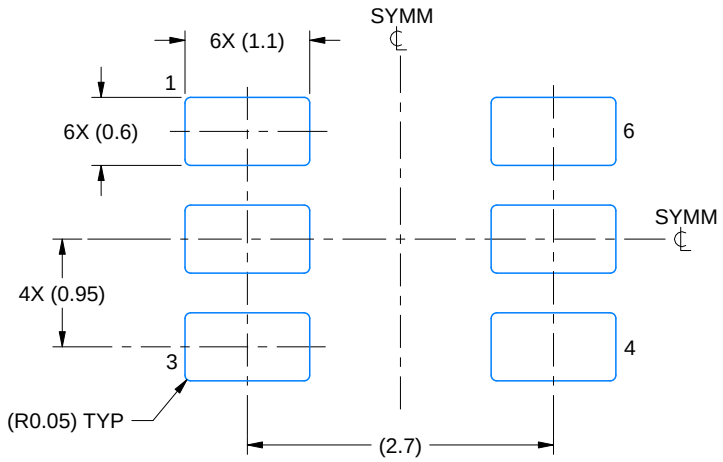
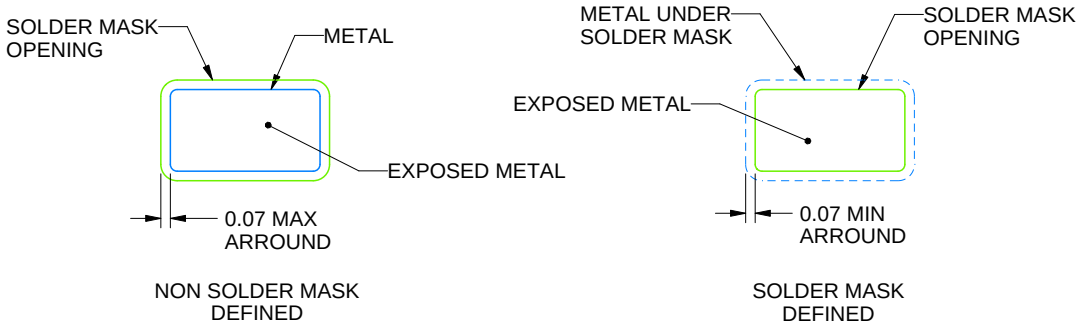
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-193.



LAND PATTERN EXAMPLE
EXPLOSED METAL SHOWN
SCALE:15X



SOLDERMASK DETAILS

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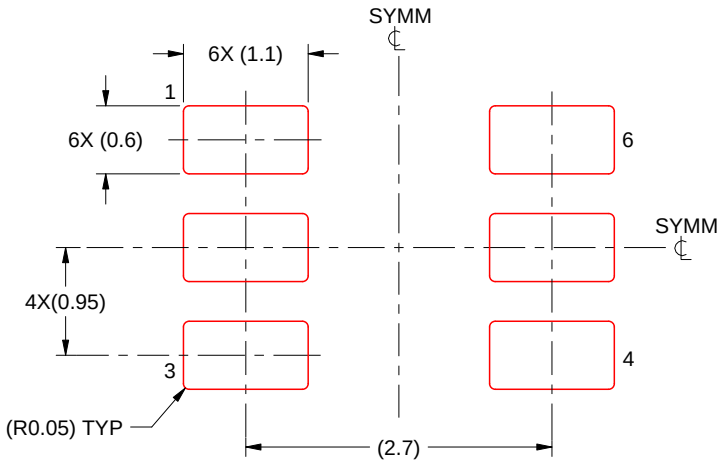
NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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